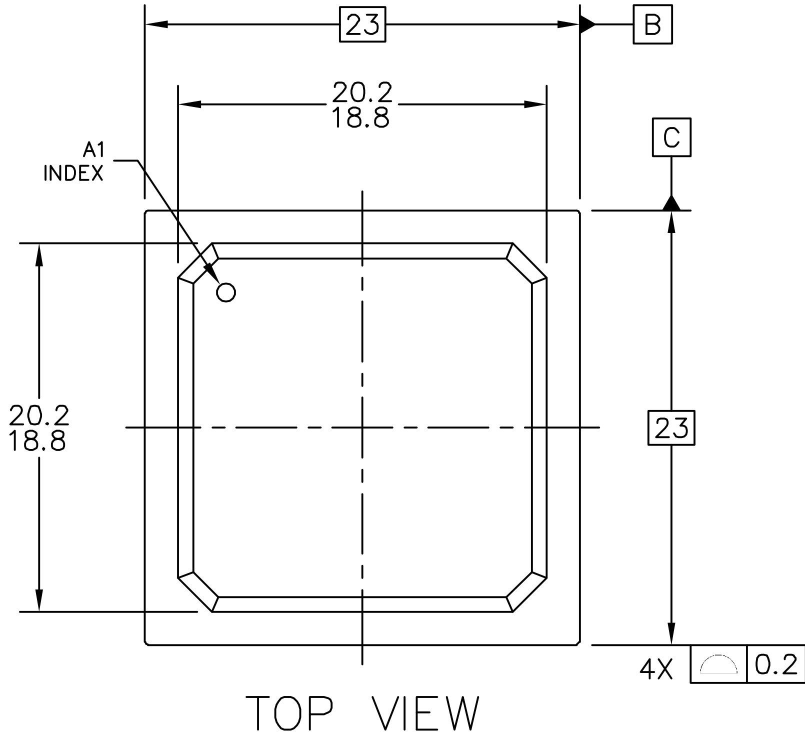

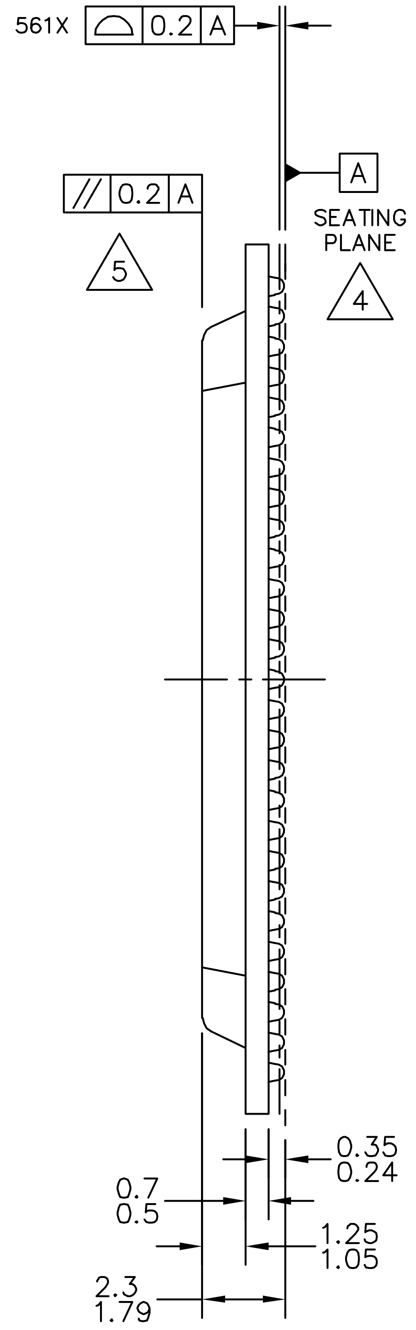

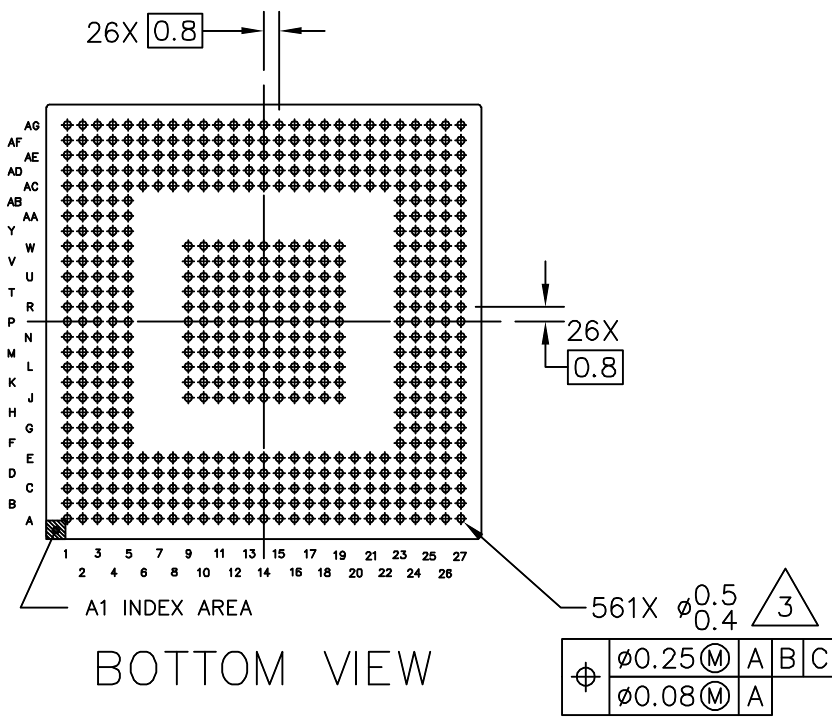

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MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE
TITLE: TEPBGA–I, 561 I/O, 23 X 23 PKG, 0.8 MM PITCH	DOCUMENT NO: 98ASA00181D REV: A
	STANDARD: NON–JEDEC
	SOT1718–1 06 JAN 2016

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.

△3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.

△4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

△5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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